



# SOD882

plastic, leadless ultra small package; 2 terminals; 0,65 mm pitch; 1 mm x 0.6 mm x 0.48 mm body

9 January 2017

Package information

## 1. Package summary

<b>Dimensions (mm)</b>	1.0 x 0.6 x 0.5
<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	DFN1006-2
<b>Package outline version code</b>	SOD882
<b>Manufacturer package code</b>	SOD882
<b>Package type industry code</b>	DFN1006-2
<b>Package outline version description</b>	plastic, leadless ultra small package; 2 terminals; 0,65 mm pitch; 1 mm x 0.6 mm x 0.48 mm body
<b>Package style descriptive code</b>	SOD (small outline diode)
<b>Package body material type</b>	P
<b>Handling precautions</b>	IC26_CHAPTER_3_2000
<b>Thermal design considerations</b>	SC18_1999_CHAPTER_5_2
<b>Mounting method type</b>	S (surface mount)
<b>Generic mounting and soldering information</b>	AN10365_3
<b>Reflow soldering footprint</b>	SOD882_fr
<b>Package life cycle status</b>	REL
<b>Major version date</b>	18-9-2008
<b>Minor version date</b>	17-7-2012
<b>Security status</b>	COMPANY PUBLIC
<b>Modified date</b>	28-11-2012
<b>Issue date</b>	26-8-2014
<b>Web publication date</b>	28-11-2012
<b>Initial web publication date</b>	18-1-2011
<b>Customer specific indicator</b>	N
<b>Maturity</b>	Product
<b>Package author</b>	Achatz Franz
<b>Package approver</b>	Elenbaas Herman

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
A <sub>2</sub>	package height	-	-	0.5	-	mm
A	seated height	0.46	-	0.48	0.5	mm
D	package length	0.55	-	0.6	0.62	mm



plastic, leadless ultra small package; 2 terminals; 0,65 mm pitch; 1 mm x 0.6 mm x 0.48 mm body

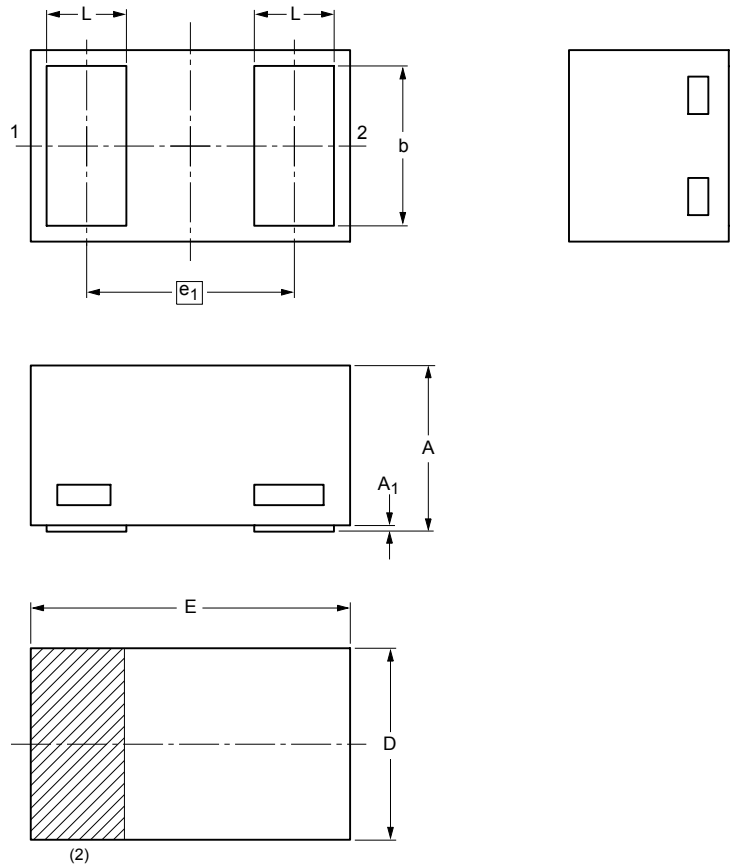
Symbol	Parameter		Min	Typ	Nom	Max	Unit
E	package width		0.95	-	1	1.02	mm
e	nominal pitch		-	-	0.65	-	mm
n <sub>2</sub>	actual quantity of termination		-	-	2	-	

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## 2. Package outline

DFN1006-2: Leadless ultra small plastic package; 2 terminals; body 1.0 x 0.6 x 0.5 mm

SOD882



Dimensions (mm are the original dimensions)

Unit	A <sup>(1)</sup>	A <sub>1</sub>	b	D	E	e <sub>1</sub>	L
mm	max 0.50	0.03	0.55	0.62	1.02	0.30	
	nom					0.65	
	min 0.46		0.47	0.55	0.95		0.22

Note

- Including plating thickness
- The marking bar indicates the cathode (if applicable)

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOD882					<del>14-08-26</del> 14-08-27

Fig. 1. Package outline DFN1006-2 (SOD882)

plastic, leadless ultra small package; 2 terminals; 0,65 mm pitch; 1 mm x 0.6 mm x 0.48 mm body

### 3. Soldering

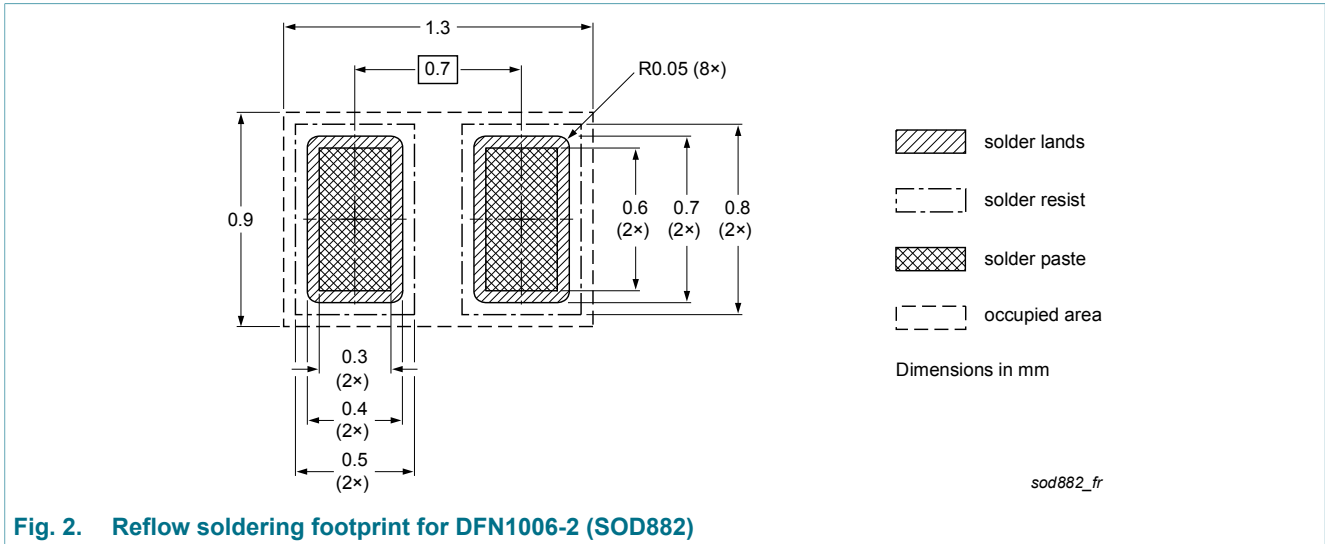


Fig. 2. Reflow soldering footprint for DFN1006-2 (SOD882)

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## 4. Legal information

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